

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10	lead with substrate same underfill and 257/738.ccls.	USPAT	OR	ON	2005/10/15 19:25
L2	5	lead with substrate same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2005/10/15 19:26
L3	5	("5349238"   "5442229"   "5825081"   "6603071"   "6744120").PN. OR ("6867490").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 19:25
L4	6	lead with bump same underfill same bump same solder near (resist layer)	USPAT	OR	ON	2005/10/15 19:27
L5	6	lead with bump same underfill same solder near (resist layer)	USPAT	OR	ON	2005/10/15 19:27
L6	10757	lead with bump ssame solder near (resist layer)	USPAT	OR	ON	2005/10/15 19:27
L7	4420	lead with bump ssame solder near (resist layer)and 257/738.ccls.	USPAT	OR	ON	2005/10/15 19:27
L8	16	lead with bump same solder near (resist layer)and 257/738.ccls.	USPAT	OR	ON	2005/10/15 19:27
L9	4	("4280132"   "5953814"   "6157085"   "6287895").PN. OR ("6710458").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 19:30
L10	33	("4604644"   "5084961"   "5089440"   "5121190"   "5194930"   "5274913"   "5400950"   "5542601"   "5578525"   "5615477"   "5704116"   "5710071").PN. OR ("5953814").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 19:38
L11	1	"5,656,862".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 19:39
L12	38	lead with substrate with bump and 257/786.ccls.	USPAT	OR	ON	2005/10/15 21:40
L13	13	lead with substrate with bump and 257/782.ccls.	USPAT	OR	ON	2005/10/15 21:40
L14	33	lead with substrate with bump and 257/783.ccls.	USPAT	OR	ON	2005/10/15 21:40
L15	75	12 13 14	USPAT	OR	ON	2005/10/15 21:41
L16	75	12 13 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:41
L17	2	"20040061240".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42

L18	2608	(257/778).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 21:42
L19	2	"20040207084".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42
L20	0	L19 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42
L21	338	L18 and substrate with tape	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42
L22	258	L18 and substrate with tape	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42
L23	65	L22 and underfill	USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/15 21:42
L24	157	("4604644"   "4825284"   "4970575"   "4987100"   "5107325"   "5177669"   "5222014"   "5239198"   "5249101"   "5291062"   "5311402").PN. OR ("5450283").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L25	40	L18 and surfactant	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L26	1	"6,576,495".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L27	1996	tape with substrate with made	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L28	484	L27 and "257"\$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L29	11	("5918364"   "5939783"   "5985456"   "6013417"   "6044550"   "6165885"   "6281046"   "6316830"   "6319751").PN. OR ("6445075"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42

L30	5	(US-6445075-\$ or US-6576495-\$ or US-6661104-\$ or US-6724091-\$ or US-6819004-\$).did.	USPAT	OR	ON	2005/10/15 21:42
L31	121	lead with substrate with bump and 257/778.ccls.	USPAT	OR	ON	2005/10/15 21:42
L32	5	("4624724"   "5538771"   "5614316"   "5670251").PN. OR ("6498400").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L33	21	("2671844"   "3488840"   "4661192"   "4706811"   "4758407"   "4806309"   "5120678"   "5154341"   "5269453"   "5282565"   "5346857"   "5352407"   "5410184"   "5411703"   "5527628").PN. OR ("6436730").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L34	16	("4706811"   "4758407"   "5120678").PN. OR ("5410184").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/15 21:42
L35	81	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2005/10/15 21:42
L36	81	lead with substrate with bump and 257/738.ccls.	USPAT	OR	ON	2005/10/15 21:42